

**PACKAGE RELIABILITY REPORT
FOR**

DSQ3301-K01 Contactor

Dallas Semiconductor

4401 South Beltwood Parkway
Dallas, TX 75244-3292

Prepared by:

Ken Wendel

Ken Wendel
Reliability Engineering Manager
Dallas Semiconductor
4401 South Beltwood Pkwy.
Dallas, TX 75244-3292
Email : ken.wendel@dalsemi.com
ph: 972-371-3726
fax: 972-371-6016
mbl: 214-435-6610

Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor packages:

DSQ3301-K01 Contactor

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at <http://www.maxim-ic.com/TechSupport/dsreliability.html>.

Package Description:

A description of this assembly can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.

Note: Due to the nature of the construction on this assembly, there is no operating life data collected.

The reliability data follows. Some of the data in this report may be generic. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. If there are additional assemblies used as part of this report, a description of each will follow which includes the respective reliability data for that assembly. Where appropriate, preconditioning is performed before all stresses and the bond crater test unless otherwise noted. The reliability data section includes the latest data available.

Assembly Information:

Assembly Site:	CIRTEK
Pin Count:	2
Package Type:	SFN (Pb-Free)
Body Size:	6x6x0.88
Mold Compound:	Sumitomo G600 with Plasma before molding
Lead Frame:	Stamped Copper CDA194
Lead Finsh:	NiPdAu
Die Attach:	84-1 LMISR4 Epoxy Silverfilled Ablebond
Bond Wire / Size:	Au / 1.0 mil
Flammability:	UL 94-V0
Theta JA:	
Theta JC:	
Moisture Sensitivity (JEDEC J-STD20A)	Level 1
Date Code Range:	0626 to 0626

DATE CODE: 0626 **LOT NUMBER:** SFNContactor

MECHANICAL LIFE

DESCRIPTION	CONDITION	READPOINT	QTY	FAILS	FA#
MECHANICAL SHOCK	200G, 1/2 SINE, 6 MS	30 CYS	48	0	
Total:				0	

FOLLOWED BY:**TEMPERATURE CYCLE**

DESCRIPTION	CONDITION	READPOINT	QTY	FAILS	FA#
TEMP CYCLE	-55C TO 125C	1000 CYS	48	0	
Total:				0	

MECHANICAL LIFE

DESCRIPTION	CONDITION	READPOINT	QTY	FAILS	FA#
VIBRATION, VARIABLE FREQUENCY	10g or 0.06", 5Hz-2KHz, X Y Z axis	30 HRS	48	0	

FOLLOWED BY:

Total: 0

TEMPERATURE HUMIDITY BIAS

DESCRIPTION	CONDITION	READPOINT	QTY	FAILS	FA#
BIASED MOISTURE	85/85, 5.5 VOLTS	1000 HRS	48	0	
		Total:		0	